

## 信頼性試験成績書

### 0.18um Process Technology Product and Package Legacy Fujitsu Reliability Engineering Test Report

Wafer Process : Aizu Fujitsu  
Assembly : J-Devices

## Reliability Test 1

Device Type : MCU 1  
Package Type : Plastic LQFP-100 Package

Test Item	Test Condition	Tested Number	Tested Time	Failed Number
High Temperature Operation Life 高温連続動作試験	125 °C V <sub>DD</sub> =Maximum Rating	231 (77x3Lots)	(a) 2000h	0
High Temperature Storage 高温保存試験	150 °C	231 (77x3Lots)	(a) 2000h	0
Temperature Cycling 温度サイクル	-65°C~150°C	231 (77x3Lots)	(a) 1000cyc	0
Unbiased HAST	130°C, 85%RH	231 (77x3Lots)	(a) 144h	0
HAST	130°C, 85%RH V <sub>DD</sub> =Maximum Rating	231 (77x3Lots)	(a) 144h	0

(a) Pre-condition: Baking (125°C, 24h) +Moisture Absorption (30°C/60%RH, 192h) +IR 260°C Max. x3

## Document History Page

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**	5769781	KUMI	Initial release.